X7R with KONNEKT™ Technology, 25 - 3,000 VDC (Commercial & Automotive Grade)











Overview

KEMET's X7R with KONNEKT™ technology surface mount capacitors are designed for applications where higher capacitance and voltage are needed without requiring additional board space. KONNEKT high density packaging technology uses an innovative Transient Liquid Phase Sintering (TLPS) material to create a surface mount multichip solution for high density packaging.

KEMET's X7R dielectric features a 125°C maximum operating temperature and is considered temperature stable. The Electronics Components, Assemblies and Materials Association (EIA) characterizes X7R dielectric as a Class II material. Components of this classification are fixed, ceramic dielectric capacitors suited for bypass and decoupling applications or for frequency

discriminating circuits where Q and stability of capacitance characteristics are not critical. X7R exhibits a predictable change in capacitance with respect to time and voltage, boasting a minimal change in capacitance with reference to ambient temperature. Capacitance change is limited to ±15% from -55°C to +125°C.

In addition to their use in power supplies, these capacitors can be used in industries related to automotive (hybrid), telecommunications, medical, military, aerospace, semiconductors and test/diagnostic equipment.

Automotive Grade devices are also available which meet the demanding Automotive Electronics Council's AEC-Q200 qualification requirements

Benefits

- Commercial and Automotive Grade (AEC-Q200)
- · Industry-leading CV values
- Capacitance offerings ranging from 2.4 nF 20 μF
- DC voltage ratings from 25 2,000 V
- EIA 1812 and 2220 case sizes
- Operating temperature range of -55°C to +125°C
- Low ESR and ESL
- · Non-polar device, minimizing installation concerns
- · Lead (Pb)-free, RoHS, and REACH compliant
- · Surface mountable using standard MLCC reflow profiles

Applications

- SMPS (Switch Mode Power Supplies)
- · Lighting ballasts, HID lighting
- DC/DC Converters
- Telecom equipment
- Industrial and medical equipment
- Filters
- Snubbers
- DC Blocking
- Bypass





Ordering Information

С	1812	С	944	K	С	R	L	С	XXXX
Ceramic	Case Size (L"x W")	Specification/ Series	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (V)	Dielectric	Subclass Designation	Termination Finish	Orientation and Packaging (Suffix/C-Spec)
С	1812 2220	C = Standard	Two single digits + number of zeros.	K = ±10% M = ±20%	3 = 25 V 5 = 50 V 1 = 100 V 2 = 200 V A = 250 V C = 500 V B = 630 V D = 1,000 V F = 1,500 V G = 2,000 V Z = 2,500 V H = 3,000 V	R = X7R	L = KONNEKT	C = 100% matte Sn	See "Packaging and Orientation C-Spec Ordering Options Table"

Packaging C-Spec Ordering Options Table

Packaging Type	Mounting Orientation ¹	Packaging/Grade Ordering Code (C-Spec)					
Commercial Grade							
7" Reel/Unmarked		TU					
13" Reel/Unmarked		7210					
	Automotive Grade						
7" Reel/Unmarked		AUTO					
13" Reel/Unmarked		AUT07210					

¹ All parts are shipped in standard orientation which refers to the positioning of the KONNEKT capacitors in the Tape and Reel pockets.



Automotive C-Spec Information

KEMET automotive grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. These products are supported by a Product Change Notification (PCN) and Production Part Approval Process warrant (PPAP).

Automotive products offered through our distribution channel have been assigned an inclusive ordering code C-Spec, "AUTO." This C-Spec was developed in order to better serve small and medium-sized companies that prefer an automotive grade component without the requirement to submit a customer Source Controlled Drawing (SCD) or specification for review by a KEMET engineering specialist. This C-Spec is therefore not intended for use by KEMET OEM automotive customers and are not granted the same "privileges" as other automotive C-Specs. Customer PCN approval and PPAP request levels are limited (see details below.)

Product Change Notification (PCN)

The KEMET product change notification system is used to communicate primarily the following types of changes:

- Product/process changes that affect product form, fit, function, and/or reliability
- · Changes in manufacturing site
- Product obsolescence

KEMET Automotive	Customer Notifica	tion Due To:	Days Prior To	
C-Spec	Process/Product change	Obsolescence*	Implementation	
KEMET assigned ¹	Yes (with approval and sign off)	Yes	180 days minimum	
AUT0	Yes (without approval)	Yes	90 days minimum	

¹ KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

Production Part Approval Process (PPAP)

The purpose of the Production Part Approval Process is:

- To ensure that supplier can meet the manufacturability and quality requirements for the purchased parts.
- To provide the evidence that all customer engineering design records and specification requirements are properly understood and fulfilled by the manufacturing organization.
- To demonstrate that the established manufacturing process has the potential to produce the part.

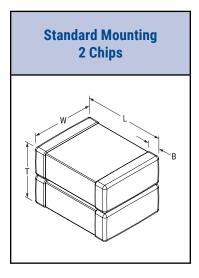
KEMET Automotive		PPAP (Product Part Approval Process) Level							
C-Spec	1	2	3	4	5				
KEMET assigned ¹	•	•	•	•	•				
AUT0			0						

¹ KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

- Part number specific PPAP available
- Product family PPAP only



Dimensions - Millimeters (Inches)



Number of Chips	Mounting	EIA SIZE CODE	METRIC SIZE CODE	L LENGTH	W WIDTH	T THICKNESS	B BANDWIDTH	Mounting Technique
2	Ottomologia	1812	4532	4.50 (0.177) ±0.30 (0.012)	3.2 (0.126) ±0.3 (0.012)	See Table 1A	0.60 (0.024) ±0.35 (0.014)	Solder Reflow
2	Standard 2		5750	5.70 (0.224) ±0.40 (0.016)	5.00 (0.197) ±0.40 (0.016	for Thickness	0.60 (0.024) ±0.35 (0.014	Only



Table 1A - 1812 Product Ordering Codes, Ratings, and Package Quantities

				Number		Typical	Tape & Red	el Quantity
KEMET Part Number ¹	Capacitance	Cap Code	Voltage	of Chips	Thickness mm (inch)	Average Piece Weight (g)	7" Tape & Reel	13" Tape & Reel
C1812C206(a)3RLC(b)	20 μF	206	25 V		3.30 (0.130) ±0.40 (0.16)	0.25	500	2,000
C1812C945(a)5RLC(b)	9.4 μF	945	50 V		3.30 (0.130) ±0.40 (0.16)	0.25	500	2,000
C1812C665(a)1RLC(b)	6.6 µF	665	100 V		3.90 (0.153) ±0.40 (0.16)	0.28	275	1,050
C1812C944(a)2RLC(b)	0.94 μF	944	200 V		3.50 (0.138) ±0.30 (0.12)	0.25	500	2,000
C1812C944(a)ARLC(b)	0.94 μF	944	250 V		3.50 (0.138) ±0.30 (0.12)	0.25	500	2,000
C1812C664(a)CRLC(b)	0.66 μF	664	500 V	2	4.30 (0.169) ±0.20 (0.008)	0.30	250	1,000
C1812C304(a)BRLC(b)	0.3 μF	304	630 V	2	3.50 (0.138) ±0.40 (0.16)	0.25	500	2,000
C1812C204(a)DRLC(b)	0.2 μF	204	1,000 V		3.50 (0.138) ±0.30 (0.12)	0.25	500	2,000
C1812C663(a)FRLC(b)	0.066 μF	663	1,500 V		5.10 (0.201) ±0.40 (0.16)	0.35	200	900
C1812C203(a)GRLC(b)	0.044 μF	203	2,000 V		5.10 (0.201) ±0.40 (0.016)	0.35	200	900
C1812C942(a)ZRLC(b)	0.0094 μF	942	2,500 V		5.10 (0.201) ±0.40 (0.016)	0.35	200	900
C1812C242(a)HRLC(b)	0.0024 μF	242	3,000 V		5.10 (0.201) ±0.40 (0.016)	0.35	200	900

¹ Complete part number requires additional characters in the numbered positions provided in order to indicate capacitance tolerance and grade. For each numbered position, available options are as follows:

⁽a) Capacitance tolerance character "K" or "M."

⁽b) Product Grade: "TU" for Commercial or "AUTO" for Automotive



Table 1B - 2220 Product Ordering Codes, Ratings, and Package Quantities

				Number		Typical	Tape & Red	Tape & Reel Quantity	
KEMET Part Number ¹	Capacitance	Cap Code	Voltage	of Chips	Thickness mm (inch)	Average Piece Weight (g)	7" Tape & Reel	13" Tape & Reel	
C2220C206(a)5RLC(b)	20 μF	206	50 V		4.90 (0.193) ±0.30 (0.11)	0.78	225	900	
C2220C205(a)1RLC(b)	2 μF	205	100 V		3.1 (0.122) ±0.30 (0.11)	0.47	500	1,925	
C2220C205(a)2RLC(b)	2 μF	205	200 V		3.1 (0.122) ±0.30 (0.11)	0.47	500	1,925	
C2220C205(a)ARLC(b)	2 μF	205	250 V		3.1 (0.122) ±0.30 (0.11)	0.47	500	1,925	
C2220C944(a)CRLC(b)	0.94 μF	944	500 V		5.1 (0.200) ±0.40 (0.016)	0.81	300	1,250	
C2220C664(a)BRLC(b)	0.66 μF	664	630 V	2	5.1 (0.200) ±0.40 (0.016)	0.80	300	1,250	
C2220C244(a)DRLC(b)	0.24 μF	244	1,000 V		5.1 (0.200) ±0.40 (0.016)	0.80	300	1,250	
C2220C164(a)FRLC(b)	0.16 μF	164	1,500 V		5.1 (0.200) ±0.40 (0.016)	0.79	300	1,250	
C2220C443(a)GRLC(b)	0.044 μF	443	2,000 V		5.1 (0.200) ±0.40 (0.016)	0.80	300	1,250	
C2220C303(a)ZRLC(b)	0.030 μF	303	2,500 V		5.1 (0.200) ±0.40 (0.016)	0.80	300	1,250	
C2220C303(a)HRLC(b)	0.030 μF	303	3,000 V		5.1 (0.200) ±0.40 (0.016)	0.80	300	1,250	

¹ Complete part number requires additional characters in the numbered positions provided in order to indicate capacitance tolerance and grade. For each numbered position, available options are as follows:

⁽a) Capacitance tolerance character "K" or "M."

⁽b) Product Grade: "TU" for Commercial or "AUTO" for Automotive



Performance and Reliability: Test Methods and Conditions (Commercial Only)

Test	Reference	Test Condition	Limits					
Visual and Mechanical	KEMET Internal	No defects that may affect performance (10X)		D	imensions acc	ording KEMET S	pec Sheet	
Capacitance (Cap)	KEMET Internal	C ≤ 10 μF 1 kHz ±50 Hz and 1.0 ±0.2 V_{rms} C > 10 μF 120 Hz ±10 Hz and 0.5 ±0.1 V_{rms} Capacitance measurements (including tolerance) are indexed to a referee time of 1,000 hours	Within Tolerance					
		0.410.05			Withi	n Specification		
Dissipation	KEMET	$C \le 10 \mu F$ Frequency: 1 kHz ±50 Hz Voltage: 1.0 ±0.2 V_{rms} , 0.5 ±0.2 V_{rms}		EIA Caso Size		Capacitance	Dissipation Factor (Maximum %)	
Factor (DF) Internal		C > 10 μF Frequency: 120 Hz ±10 Hz		1812		< 20 μF	2.5	
		Voltage: 0.5 ±0.1 V _{rms}	-	2220	ALL	20 μF ALL	2.5	
				2220		ALL	2.3	
			To o	obtain I	R limit, divide N	n Specification 1Ω-μF value by t	he capacitance and of the two limits.	
		Apply rated voltage for 120 seconds at 25°C		EIA Rated DC Voltage		IR Limit		
Insulation	KEMET Internal				25 – 100 V	500 megaohm n	nicrofarads or 10 GΩ	
Resistance (IR)				1812	200 - 250 V	-	nicrofarads or 100 GΩ	
					500 - 1,000 V 1,500 - 3,000 V	100 megaohm microfarads or 10 GΩ 1,000 megaohm microfarads or 100 GΩ		
					50 – 100 V		nicrofarads or 10 GΩ	
				2220	200 – 250 V	1,000 megaohm microfarads or 100 GΩ		
					500 - 630 V	100 megaohm microfarads or 10 GΩ		
					1,000 - 3,000 V	1,000 megaohm n	nicrofarads or 100 GΩ	
Temperature Coefficient of Capacitance Internal (TCC)		C ≤ 10µF Frequency: 1 kHz ±50 Hz Voltage*: 1.0 ±0.2 V _{rms} C > 10µF Frequency: 120 Hz ±10 Hz Voltage: 0.5 ±0.1 V _{rms} * See part number specification sheet for voltage Step Temperature (°C)				tance ±15% over °C to +125°C	r	
(100)		1 +25°C 2 -55°C 3 +25°C (Reference) 4 +125°C						



Performance and Reliability: Test Methods and Conditions (Commercial Only) cont.

Test	Reference	Test Condition	Limits
Dielectric Withstanding Voltage (DWV)	KEMET Internal	Rated DC Voltage (% of Rated) < 500	Cap: Initial Limit DF: Initial Limit IR: Initial Limit Withstand test voltage without insulation breakdown or damage.
Aging Rate (Maximum % Capacitance Loss/Decade Hour)	KEMET Internal	Capacitance measurements (including tolerance) are indexed to a referee time of 1,000 hours. Please refer to a part number specific datasheet for referee time details.	3% Loss/Decade Hour
Terminal Strength	KEMET Internal	Shear stress test per specific case size, Time: 60±1 seconds Case Size Force 1812 2220 18N	No evidence of mechanical damage
Board Flex	AEC-Q200-005	Standard Termination system 2.0 mm Test time: 60± 5 seconds Ramp time: 1 mm/second (Unit: mm)	No evidence of mechanical damage
Solderability	KEMET Custom Test	1. Board shear – SAC305 solder. Shear force of 1.8 kg (minimum) 2. Wetting balance – IEC 60068–2–69	Visual Inspection. 95% coverage on termination. No leaching
Temperature Cycling	JESD22 Method JA-104	1,000 cycles (-55°C to +125°C) 2 – 3 cycles per hour Soak Time 1 or 5 minutes	Measurement at 24 hours ±4 hours after test conclusion. Cap: Initial Limit DF: Initial Limit IR: Initial Limit



Performance and Reliability: Test Methods and Conditions (Commercial Only) cont.

Test	Reference	Test Condition	Limits
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C/85% RH and 200 VDC maximum. Low Volt Humidity: 1,000 hours 85°C/85% RH and 1.5 V.	Measurement at 24 hours ±4 hours after test conclusion. Within Post Environmental Limits Cap: ±20% shift IR: 10% of Initial Limit DF Limits Maximum (%) Initial Post
Moisture Resistance	MIL-STD-202 Method 106	Number of cycles required 10, 24 hours per cycle. Steps 7a and 7b not required.	Measurement at 24 hours ±4 hours after test conclusion. Within Post Environmental Limits Cap: ±20% shift IR: 10% of Initial Limit DF Limits Maximum (%) Initial Post
Thermal Shock	MIL-STD-202 Method 107	Number of cycles required 5, (-55°C to 125°C) Dwell time 15 minutes.	Cap: Initial Limit DF: Initial Limit IR: Initial Limit
High Temperature Life MIL-STD-202		1,000 hours at 125°C with 1.0 X rated voltage applied	Within Post Environmental Limits Cap: ±20% shift IR: 10% of Initial Limit DF Limits
Storage Life	Method 108	1,000 hours at 125°C, Unpowered	Maximum (%) Initial Post 2.5 3.0 3.5 5.0



Performance and Reliability: Test Methods and Conditions (Commercial Only) cont.

Test	Reference	Test Condition	Limits
Vibration	MIL-STD-202 Method 204	5 g's for 20 minutes, 12 cycles each of 3 orientations. Test from 10 – 2,000 Hz	Cap: Initial Limit DF: Initial Limit IR: Initial Limit
Mechanical Shock	MIL-STD-202 Method 213	1,500 g's 0.5 ms Half-sine, Velocity Change 15.4 feet/second (Condition F)	Cap: Initial Limit DF: Initial Limit IR: Initial Limit
Resistance to Solvents	MIL-STD-202 Method 215	Add Aqueous wash chemical OKEMCLEAN (A 6% concentrated Oakite cleaner) or equivalent. Do not use banned solvents.	Visual Inspection 10X Readable marking, no decoloration or stains. No physical damage.

Environmental Compliance



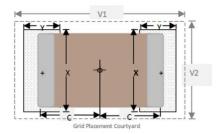




Lead (Pb)-free, RoHS, and REACH compliant without exemptions.

Land Pattern Design Recommendations per IPC-7351 (mm)

Chip Number	Orientation	EIA SIZE CODE	METRIC SIZE CODE	Median (Nominal) Land Protrusion		d		
				С	Y	Х	V 1	V2
2	Standard	1812	4532	2.05	1.40	3.50	6.00	4.00
2	Standard	2220	5750	2.65	1.50	5.40	7.30	5.90



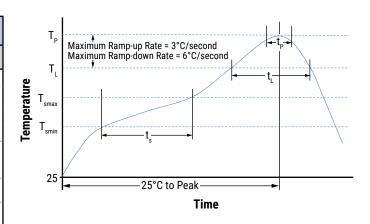


Soldering Process

Recommended Reflow Soldering Profile

KEMET's KONNEKT family of high density surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with convection and IR reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Termination Finish			
Trome readure	100% matte Sn			
Preheat/Soak				
Temperature Minimum (T _{Smin})	150°C			
Temperature Maximum (T _{Smax})	200°C			
Time (t_s) from T_{Smin} to T_{Smax}	60 - 120 seconds			
Ramp-Up Rate (T _L to T _p)	3°C/second maximum			
Liquidous Temperature (T _L)	217°C			
Time Above Liquidous (t _L)	60 - 150 seconds			
Peak Temperature (T _p)	260°C			
Time Within 5°C of Maximum Peak Temperature (t _p)	30 seconds maximum			
Ramp-Down Rate (T _P to T _L)	6°C/second maximum			
Time 25°C to Peak Temperature	8 minutes maximum			



Note: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.

Hand Soldering and Removal of KONNEKT Capacitors

The preferred method of attachment for KEMET's KONNEKT Capacitors is IR or convection reflow where temperature, time and air flow are well controlled.

However, it is understood that the manual attachment of KONNEKT capacitors is necessary for prototype and lab testing. In these instances, care must be taken not to introduce excessive temperature gradients in the KONNEKT part type that may lead to cracking in the ceramic or separation of the TLPS material.

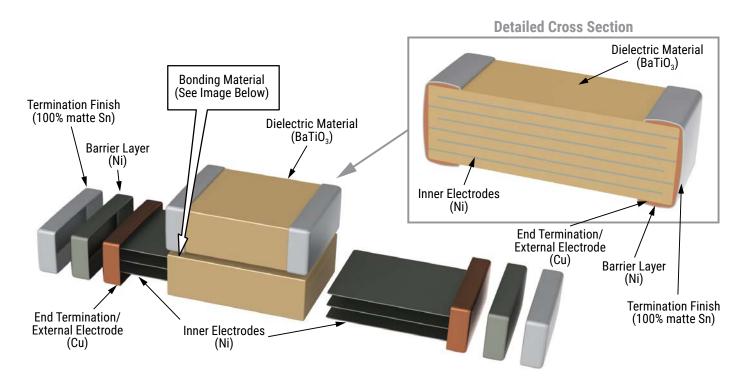
Please see KEMET's KONNEKT Soldering Guidelines here.

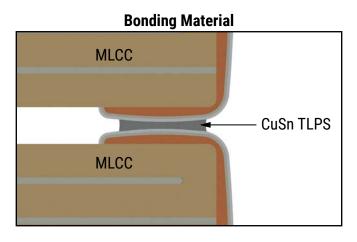


Storage & Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. In addition, temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years upon receipt.

Construction







Tape & Reel Packaging Information

KEMET offers X7R with KONNEKT technology capacitors packaged in 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 1B for details on reeling quantities for KONNEKT KC-LINK capacitors.

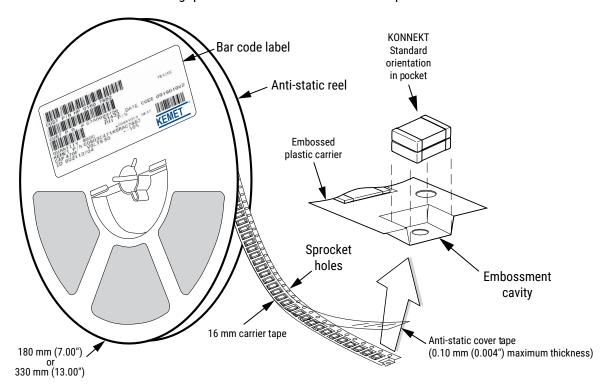


Table 4 - Carrier Tape Configuration, Embossed Plastic (mm)

EIA Case Size	Number of Chips			Embossed Plastic		
		Chip Thickness	Tape Size (W) ¹	7" Reel	13" Reel	
			(**)	Pitch (P ₁) ²		
KONNEKT 1812	2	≤ 3.5 mm	16	8	8	
		> 3.5 mm	16	12	12	
KONNEKT 2220	2	≤ 3.5 mm >5.0 mm & ≤ 5.3 mm	16	8	8	
KUNNEK I ZZZU		> 3.5 mm ≤ 5.0	10	12	12	

^{1.} Refer to Figures 1 and 2 for W and P_1 carrier tape reference locations.

^{2.} Refer to Tables 4 and 5 for tolerance specifications.



Figure 1 - Embossed (Plastic) Carrier Tape Dimensions

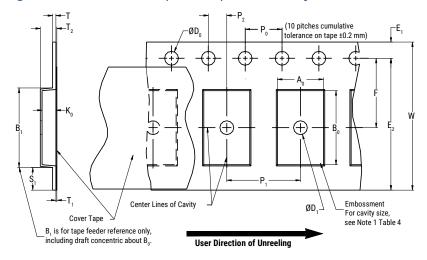


Table 5 - Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape	n	D ₁ Minimum	Е	D	D	R Reference	S ₁ Minimum	Т	T ₁
Size	D ₀	Note 1	E ₁	r ₀	r ₂	Note 2	Note 3	Maximum	Maximum
16 mm	1.5 +0.10/-0.0	1.5	1.75±0.10	4.0±0.10	2.0±0.05	30	0.600	0.600	0.100
16 mm	(0.059 +0.004/-0.0)	(0.059)	(0.069±0.004)	(0.157±0.004)	(0.079±0.002)	(1.181)	(0.024)	(0.024)	(0.004)

	Variable Dimensions — Millimeters (Inches)									
Case Size	Number of Chips	Tape Size	Pitch	B ₁ Maximum Note 4	E ₂ Minimum	F	P ₁	T ₂ Maximum	W Maximum	A ₀ ,B ₀ & K ₀
1812	2	16 mm	Triple (12mm) Double (8mm)	7.9 (0.311) 7.5 (0.295)	14.25 (0.561)	7.5±0.05 (0.138±0.002)	12.0±0.10 (0.472±0.004) 8.0±0.10 (0.315±0.004)	4.6 (0.181)	16.3 (0.642)	Note 5
2220	2	16 mm	Triple (12mm) Double (8mm)	8.5 (0.335) 9.2 (0.363)	14.25 (0.561)	7.5±0.05 (0.138±0.002)	12.0±0.10 (0.472±0.004) 8.0±0.10 (0.315±0.004)	5.9 (0.232)	16.3 (0.642)	Note 5

^{1.} The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.

- 2. The tape with or without components shall pass around R without damage (see Figure 6).
- 3. If S₁ < 1.0 mm, there may not be enough area for cover tape to be properly applied. See EIA Document 481, Paragraph 4.3 (b).
- 4. B_1 dimension is a reference dimension for tape feeder clearance only.
- 5. The cavity defined by A_{o} , B_{o} and K_{o} shall surround the component with sufficient clearance that:
- (a) the component does not protrude above the top surface of the carrier tape.
- (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
- (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3).
- (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4).
- (e) For KPS product, A_0 and B_0 are measured on a plane 0.3 mm above the bottom of the pocket.
- (f) see Addendum in EIA Document 481 for standards relating to more precise taping requirements.



Packaging Information Performance Notes

1. Cover Tape Break Force: 1.0 kg minimum.

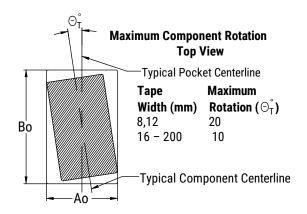
2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength		
16 mm	0.1 to 1.3 newton (10 to 130 gf)		

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300±10 mm/minute.

3. Labeling: Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

Figure 2 - Maximum Component Rotation



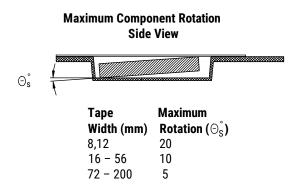


Figure 3 - Maximum Lateral Movement

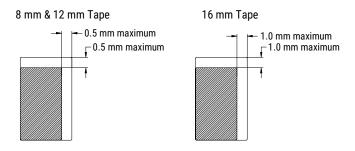
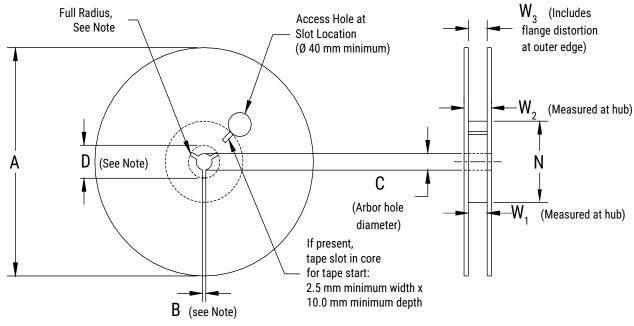




Figure 5 - Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 6 - Reel Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)							
Tape Size	A	D Minimum					
16 mm	178±0.20 (7.008±0.008) or 330±0.20 (13.000±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)			
Variable Dimensions — Millimeters (Inches)							
Tape Size	N Minimum See Note 2, Tables 2-3	W ₁	W ₂ Maximum	W ₃			
16 mm	50 (1.969)	16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	Shall accommodate tape width without interference			



Figure 6 - Tape Leader & Trailer Dimensions

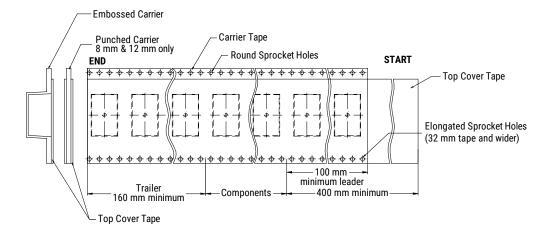
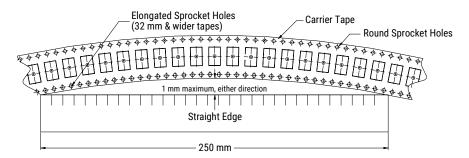


Figure 7 - Maximum Camber





KEMET Electronics Corporation Sales Offices

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